

RF Low Noise FET CE3512K2

12 GHz Super Low Noise FET in Hollow Plastic PKG

DESCRIPTION

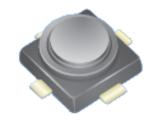
- Super Low Noise and High Gain
- Hollow (Air Cavity) Plastic package

FEATURES

• Super Low noise figure and high associated gain: NF = 0.30 dB TYP., Ga = 13.7 dB TYP. $@V_{DS} = 2 V$, I_D = 10 mA, f = 12 GHz

PACKAGE

Micro-X plastic package



APPLICATIONS

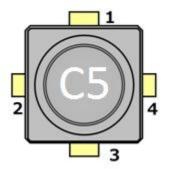
- DBS LNB gain-stage, Mix-stage
- Low noise amplifier for microwave communication systems

ORDERING INFORMATION

Part Number	Order Number	Package	Marking	Description
CE3512K2	CE3512K2-C1	Micro-X plastic package	C5	 Embossed tape 8 mm wide Pin 4 (Gate) faces the perforation side of the tape MOQ 10 kpcs/reel



PIN CONFIGURATION AND INTERNAL BLOCK DIAGRAM



Pin No.	Pin Name
1	Source
2	Drain
3	Source
4	Gate

ABSOLUTE MAXIMUM RATINGS

(TA = +25°C, unless otherwise specified)

Parameter	Symbol	Rating	Unit
Drain to Source Voltage	V _{DS}	4.0	V
Gate to Source Voltage	V _{GS}	-3.0	V
Drain Current	I _D	I _{DSS}	mA
Gate Current	l _G	80	μA
Total Power Dissipation	P _{tot}	125	mW
Channel Temperature	T _{ch}	+150	°C
Storage Temperature	T _{stg}	-55 to +125	°C
Operation Temperature	T _{op}	-55 to +125 ^{Note}	°C

Note Refer to Total Power Dissipation vs. Ambient Temperature graph on page 4

RECOMMENDED OPERATING RANGE

$(TA = +25^{\circ}C, unless otherwise specified)$					
Parameter	Symbol	MIN.	TYP.	MAX.	Unit
Drain to Source Voltage	V _{DS}	+1	+2	+3	V
Drain Current	I _D	5	10	15	mA

This document is subject to change without notice.

ELECTRICAL CHARACTERISTICS

$(TA = +25^{\circ}C, unless otherwise specified)$

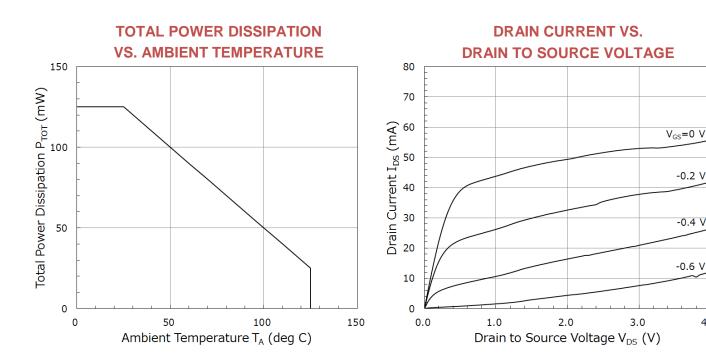
Parameter	Symbol	Condition	MIN.	TYP.	MAX.	Unit
Gate to Source Leak Current	I _{GSO}	V _{GS} = -3.0V	-	0.4	10	μA
Saturated Drain Current	I _{DSS}	$V_{DS} = 2V, V_{GS} = 0V$	27	47.5	68	mA
Gate to Source Cut-off Voltage	$V_{GS(off)}$	$V_{DS} = 2V, I_{D} = 120\mu A$	-1.10	-0.75	-0.39	V
Transconductance	Gm	$V_{DS} = 2V, I_D = 10mA$	54	69	-	mS
Noise Figure	NF	$V_{DS} = 2V, I_{D} = 10mA,$	-	0.30	0.50	dB
Associated Gain	Ga	f = 12GHz	12.5	13.7	-	dB

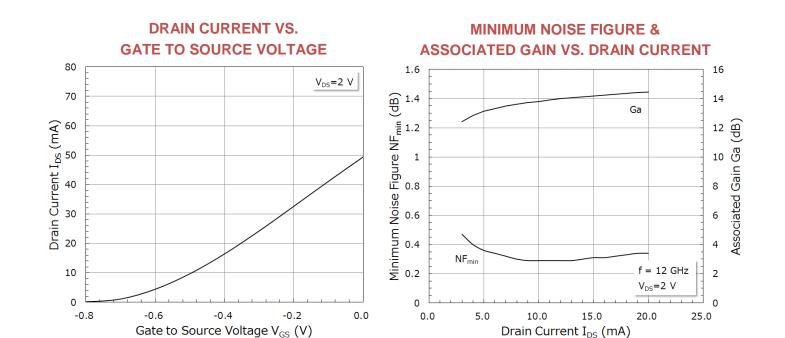
4.0



(TA=+25℃, unless otherwise specified)

CEI





S-PARAMETERS

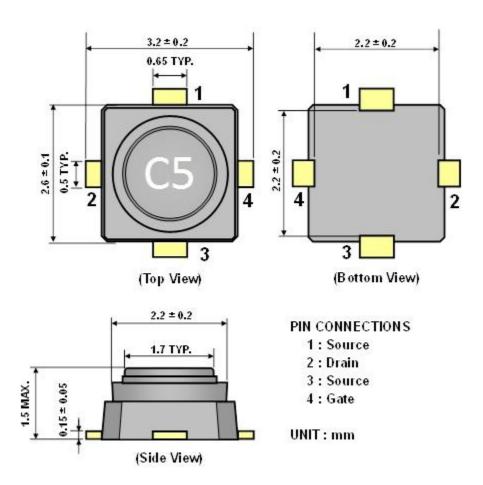
S-Parameters are available on CEL's Part Summary page under S-parameters

RECOMMENDED SOLDERING CONDITIONS

Recommended Soldering Conditions are available on CEL's Part Summary page under Associated Documents

PACKAGE DIMENSIONS

Micro-X plastic package





REVISION HISTORY

Version	Change to current version	Page(s)
CDS-0018-04 (Issue A) February 12, 2016	Initial datasheet	N/A
CDS-0018-04 (Issue B) April 27, 2016	Updated Marking Information	1, 2, 3
CDS-0018-05 (Issue A) July 29, 2016	Updated Specs in "Absolute Maximum Ratings" Table Added "Typical Characteristics" section (graphs) Added "S-Parameters" and "Recommended Soldering Conditions" sections	2, 4, 5



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CEL Headquarters • 4590 Patrick Henry Drive • Santa Clara, CA 95054 • Tel: (408) 919-2500 • www.cel.com

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